

QUALIFICATION PLAN SUMMARY

PCN #: RMES-06ZXIX068

Date: October 28, 2021

Qualification of G700LS molding compound for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site.

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at ANAP assembly site.

CCB No. 4241.001

	Assembly site	ANAP				
<u>Misc.</u>	BD Number	W35502SXU				
	MP Code (MPC)	355027G5XC01				
	Part Number (CPN)	AT17LV002-10SU				
	MSL information	MSL 1, 260C				
	Assembly Shipping Media (T/R, Tube/Tray)	Tube				
	Base Quantity Multiple (BQM)	37				
	Reliability Site	MCSO				
	Paddle size	190X300mils				
	Material	C194				
	DAP Surface Prep	Cu-Ag				
	Treatment	Roughened				
Lood From a	Process	Etched				
<u>Lead-Frame</u>	Lead-lock	Yes				
	Part Number	101420282				
	Lead Plating	Matte Sn				
	Strip Size	70x250mm				
	Strip Density	56				
Bond Wire	Material	Au				
Dia Attach	Part Number	8290				
Die Attach	Conductive	Conductive				
<u>MC</u>	Part Number	G700LS				
<u>PKG</u>	PKG Type	SOIC				
	Pin/Ball Count	20				
	PKG width/size	300mils				

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Standard Pb-free Solderability	J-STD-002D; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	5	5	1	10	> 95% lead coverage	5	MCSO	MCSO	SOIC	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability-SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	MCSO	MCSO	SOIC	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	MCSO	MCSO	SOIC	30 bonds from a min. 5 devices.
Wire Sweep								MCSO	MCSO	SOIC	
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	1	10	0	5	MCSO	MCSO	SOIC	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	1	ALL	0	5	MCSO	MCSO	SOIC	

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Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL 1, 260C	45	15	1	60	0	15	MCSO	MCSO	SOIC	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.